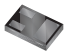
Material Composition Specification

TLM3D6D8 Case

Top View



Bottom View

Device average mass . . . . **625 µg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(µg)			(%wt)	(µg)	(ppm)
active device	doped Si	2.88%	18	Si	7440-21-3	2.88%	18	28,800
bond wire	gold	1.6%	10	Au	7440-57-5	1.60%	10	16,000
leadframe	Cu alloy	45.72%	285.75	Cu	7440-50-8	43.52%	272	435,200
				Ni	7440-02-0	1.60%	10	16,000
				Si	7440-21-3	0.32%	2.0	3,200
				Zn	7440-66-6	0.14%	0.9	1,440
				Ag	7440-22-4	0.14%	0.85	1,360
die attach	silver epoxy	0.32%	2.0	Ag	7440-22-4	0.24%	1.5	2,400
				epoxy resin	Proprietary	0.08%	0.5	800
encapsulation*	EMC GREEN	48.96%	306	silica (fused)	60676-86-0	45.92%	287	459,200
				epoxy resin	29690-82-2	1.44%	9.0	14,400
				phenol resin	9003-35-4	1.44%	9.0	14,400
				carbon black	1333-86-4	0.16%	1.0	1,600
plating	Ni/Pd/Au	0.52%	3.25	Ni	7440-02-0	0.47%	2.95	4,720
				Pd	7440-05-3	0.04%	0.25	400
				Au	7440-57-5	0.01%	0.05	80

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (11-October 2012)